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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC273

Octal D-type Flip-Flops (with Clear)



ADE-205-482 (Z)

1st. Edition

Sep. 2000




Description

This device contains 8 master-slave flip-flops with a common clock and common clear. Data on the D input having the specified setup and hold times is transferred to the Q output on the low to high transition of the clock input. The clear input when low, sets all outputs to a low state.

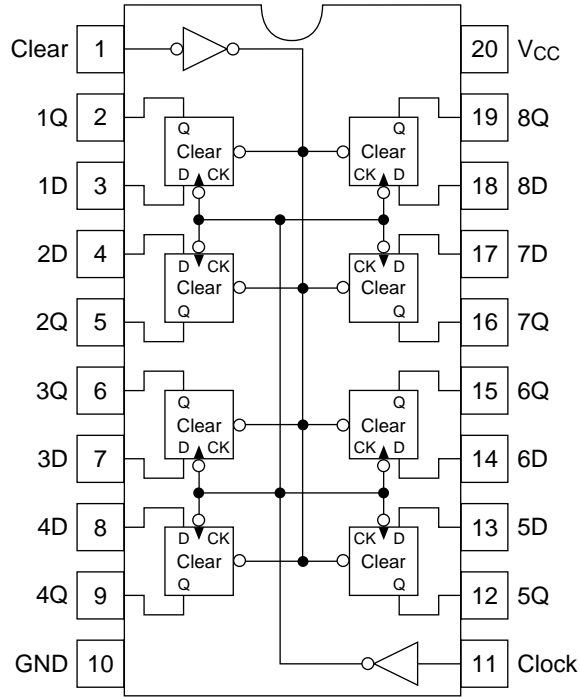
Features

- High Speed Operation: t_{pd} (Clock to Q) = 18 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

Function Table

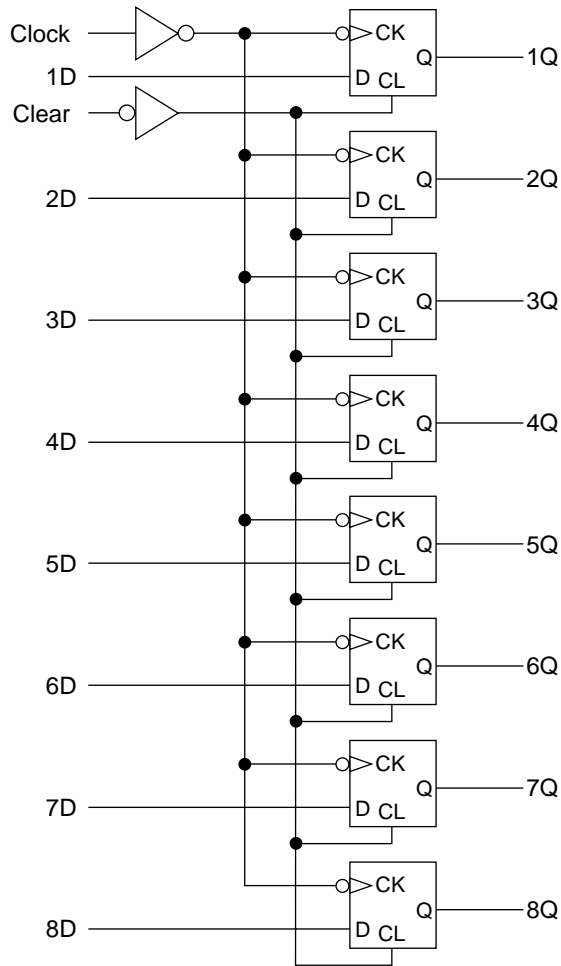
Inputs			Outputs
Clear	Clock	D	Q
L	X	X	L
H		H	H
H		L	L
H	L	X	No change
H		X	No change

Pin Arrangement



(Top view)

Logic Diagram



DC Characteristics

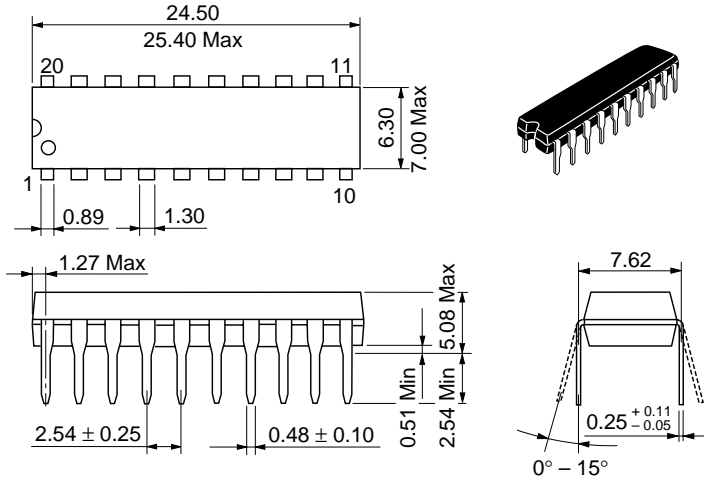
Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5		V	
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V		Vin = V _{IH} or V _{IL} I _{OH} = -20 μA
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—		I _{OH} = -4 mA	
		6.0	5.68	—	—	5.63	—		I _{OH} = -5.2 mA	
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 5.2 mA
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, I _{out} = 0 μA	

AC Characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$		$T_a = -40$ to $+85^\circ\text{C}$		Unit	Test Conditions	
			Min	Typ	Max	Min			Max
Maximum clock frequency	f_{max}	2.0	—	—	6	—	5	MHz	
		4.5	—	—	30	—	24		
		6.0	—	—	35	—	28		
Propagation delay time	t_{PHL}	2.0	—	—	145	—	180	ns	Clock to Q
		4.5	—	18	29	—	36		
		6.0	—	—	25	—	31		
	t_{PLH}	2.0	—	—	145	—	180	ns	
		4.5	—	18	29	—	36		
		6.0	—	—	25	—	31		
	t_{PHL}	2.0	—	—	145	—	180	ns	Clear to Q
		4.5	—	15	29	—	36		
		6.0	—	—	25	—	31		
Setup time	t_{su}	2.0	100	—	—	125	—	ns	Data to clock
		4.5	20	2	—	25	—		
		6.0	17	—	—	21	—		
Hold time	t_h	2.0	5	—	—	5	—	ns	Clock to data
		4.5	5	0	—	5	—		
		6.0	5	—	—	5	—		
Removal time	t_{rem}	2.0	100	—	—	125	—	ns	Clear to clock
		4.5	20	-1	—	25	—		
		6.0	17	—	—	21	—		
Pulse width	t_w	2.0	80	—	—	100	—	ns	Clock, clear
		4.5	16	8	—	20	—		
		6.0	14	—	—	17	—		
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	95	ns	
	t_{THL}	4.5	—	5	15	—	19		
	t_{THL}	6.0	—	—	13	—	16		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

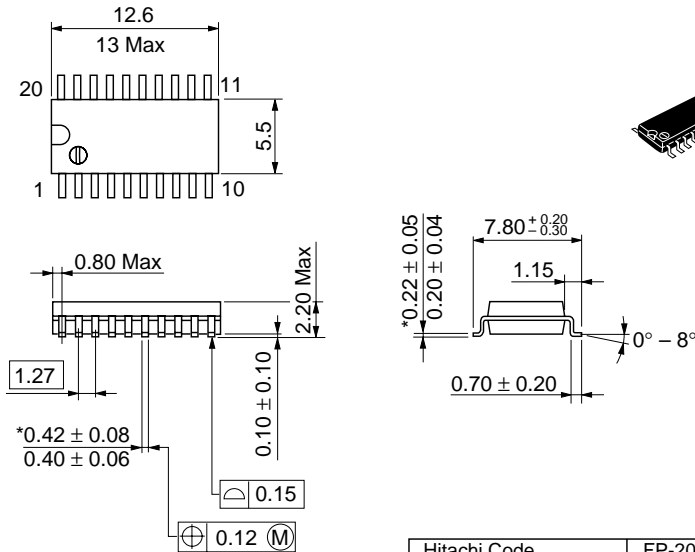
Package Dimensions

Unit: mm



Hitachi Code	DP-20N
JEDEC	—
EIAJ	Conforms
Mass (reference value)	1.26 g

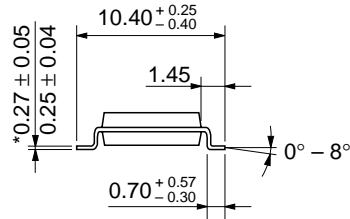
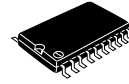
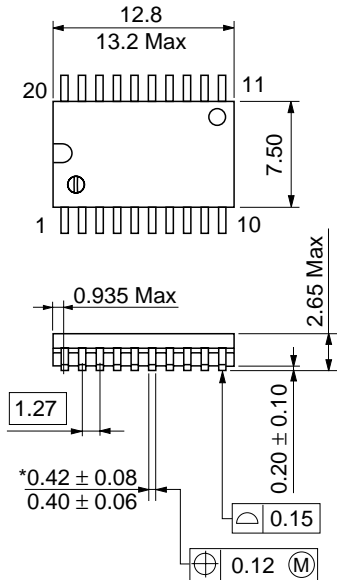
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-20DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.31 g

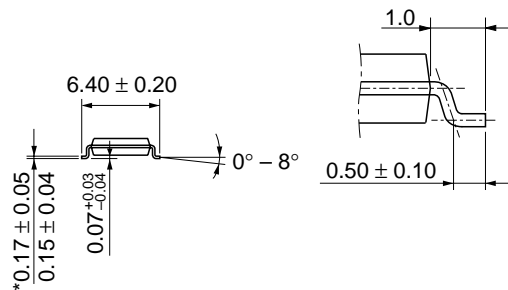
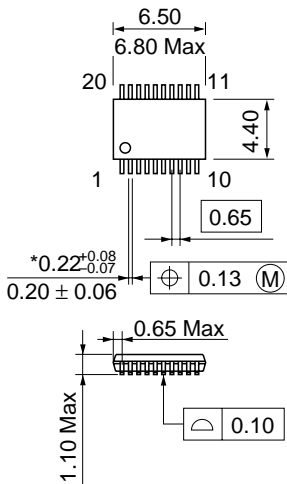
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-20DB
JEDEC	Conforms
EIAJ	—
Mass (reference value)	0.52 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	TTP-20DA
JEDEC	—
EIAJ	—
Mass (reference value)	0.07 g

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